

Click here for the 3D model.

| Dimensions |  |
| :--- | :--- |
| Chip Size | 0402 |
| L | $1 \mathrm{~mm}+/-0.05 \mathrm{~mm}$ |
| W | $0.5 \mathrm{~mm}+/-0.05 \mathrm{~mm}$ |
| T | $0.5 \mathrm{~mm}+/-0.05 \mathrm{~mm}$ |
| S | 0.3 mm MIN |
| B | $0.3 \mathrm{~mm}+/-0.1 \mathrm{~mm}$ |


| Packaging Specifications |  |
| :--- | :--- |
| Packaging | T\&R, 180mm, Paper Tape |
| Packaging Quantity | 10000 |


| General Information |  |
| :--- | :--- |
| Series | SMD Auto X8R HT150C |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra- <br> Stable, Automotive Grade |
| Features | High Temperature, Ultra-Stable, <br> Automotive Grade |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| Qualifications | AEC-Q200 |
| AEC-Q200 | Yes |
| Typical Component <br> Weight | 1.21 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |


| Specifications | 27 pF |
| :--- | :--- |
| Capacitance | 1 MHz 1.0 Vrms |
| Measurement Condition | $5 \%$ |
| Capacitance Tolerance | 50 VDC |
| Voltage DC | 125 VDC |
| Dielectric Withstanding Voltage | $-55 /+150^{\circ} \mathrm{C}$ |
| Temperature Range | X 8 R |
| Temperature Coefficient | $15 \%, 1 \mathrm{MegaHz} 1.0 \mathrm{Vrms}$ |
| Capacitance Change with Reference <br> to +25 |  |
| Dissipation Factor | $2.5 \% 1 \mathrm{MHz} 1.0 \mathrm{Vrms}$ |
| Aging Rate | $0 \%$ Loss/Decade Hour: |
| Insulation Resistance | 100 GOhms |

